

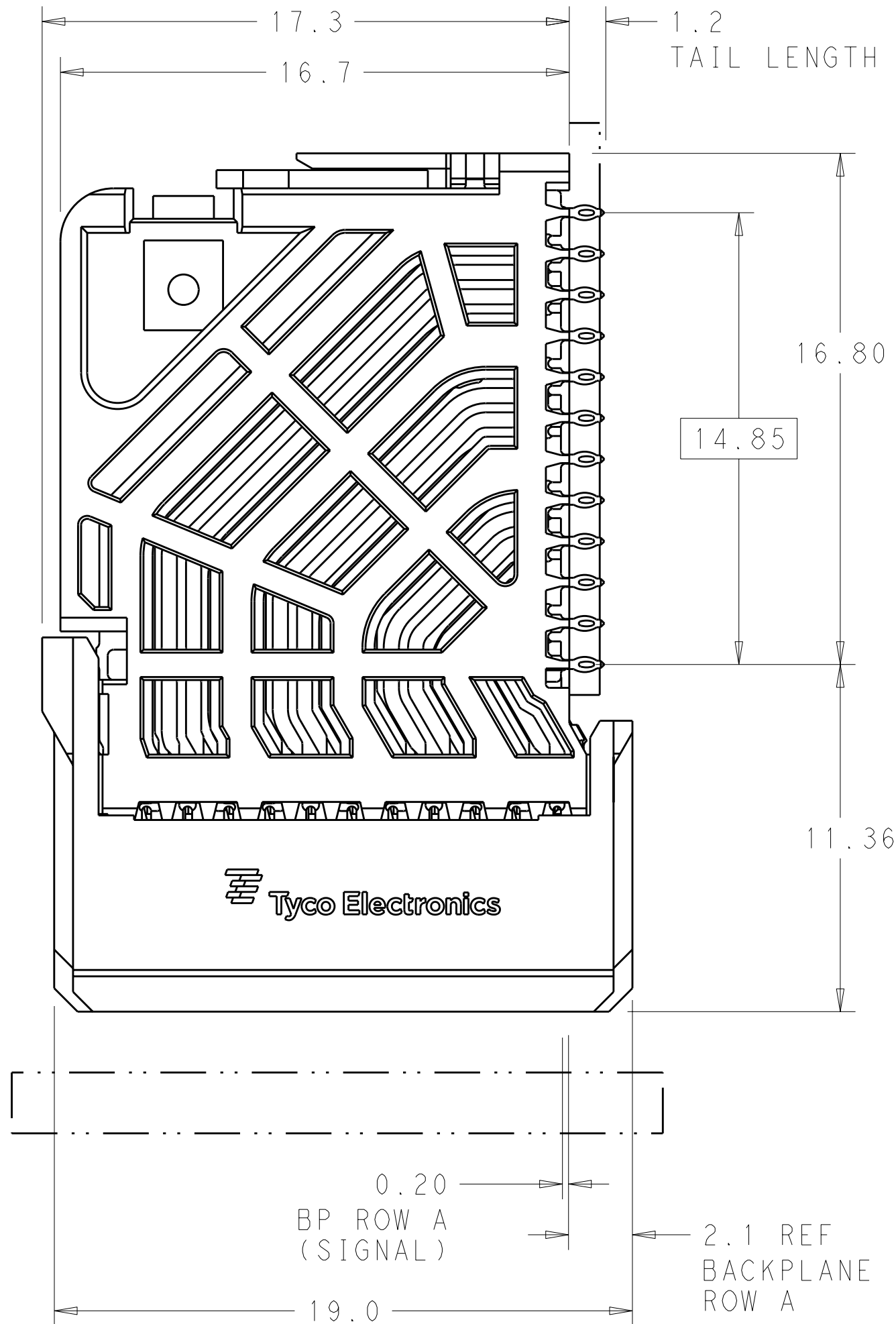
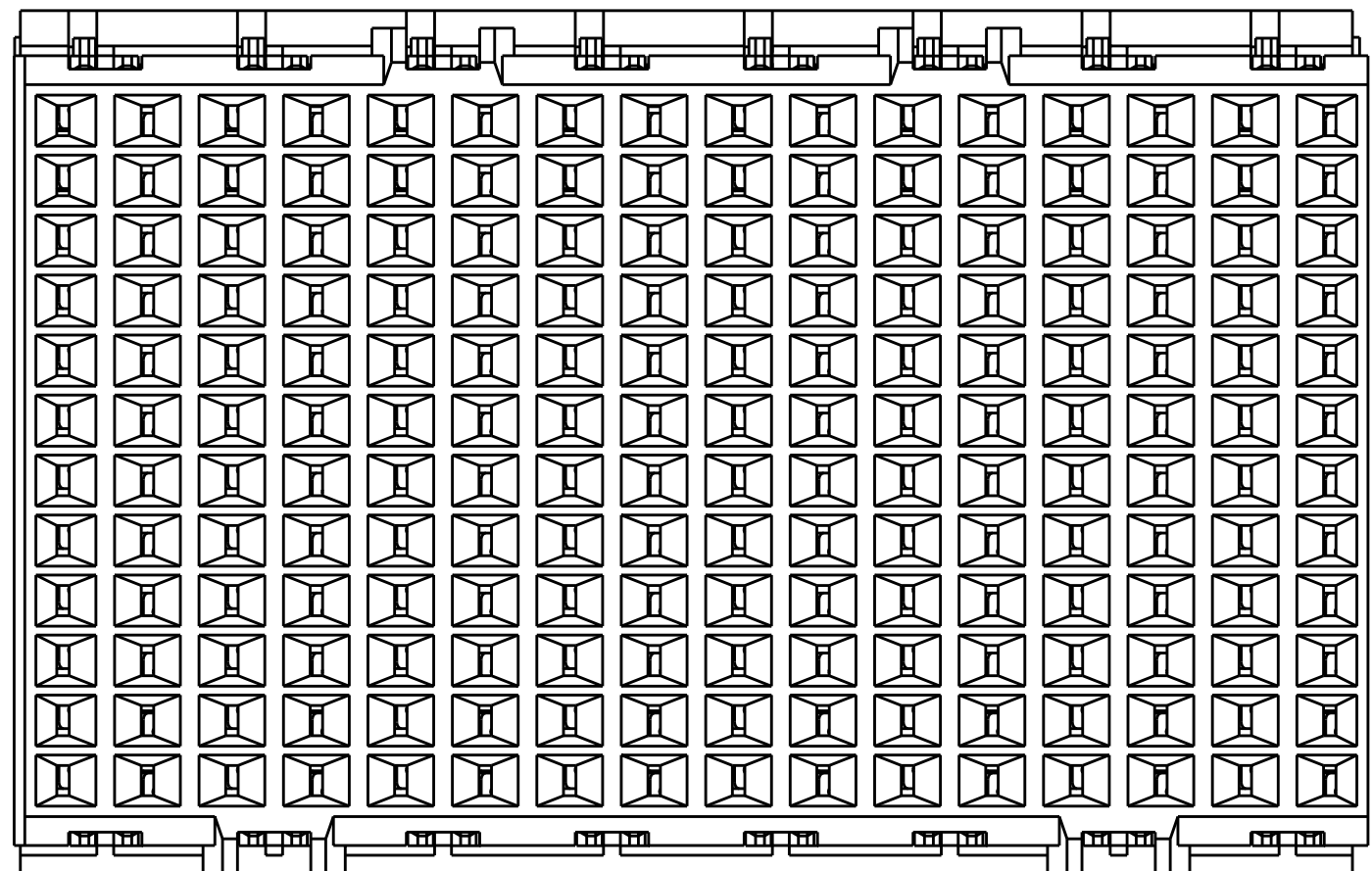
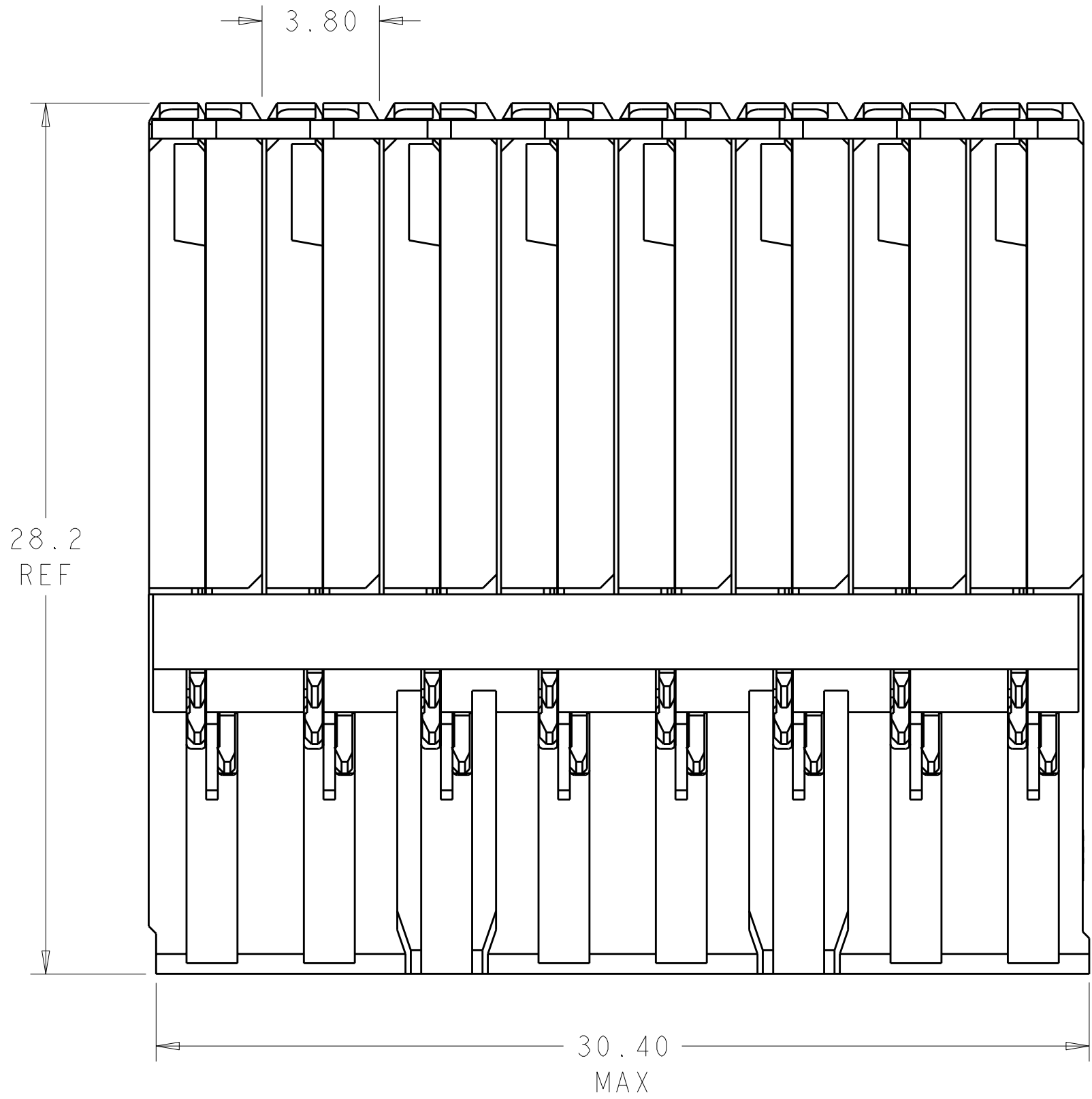
LOC		DIST		REVISONS			
P	LYR	DESCRIPTION		DATE	DWN	APVD	
	B	REVISED PER ECO-12-000418		16 JAN 2012	KH	DD	

D

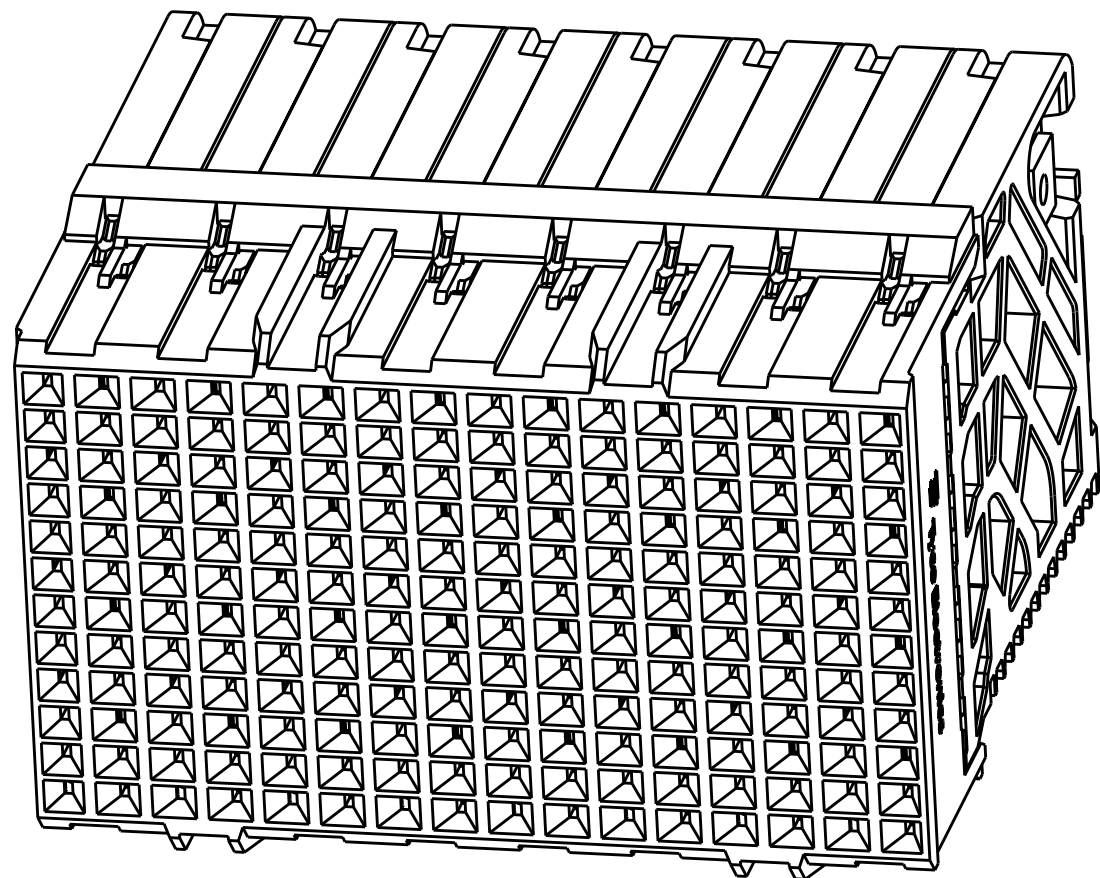
C

B

A

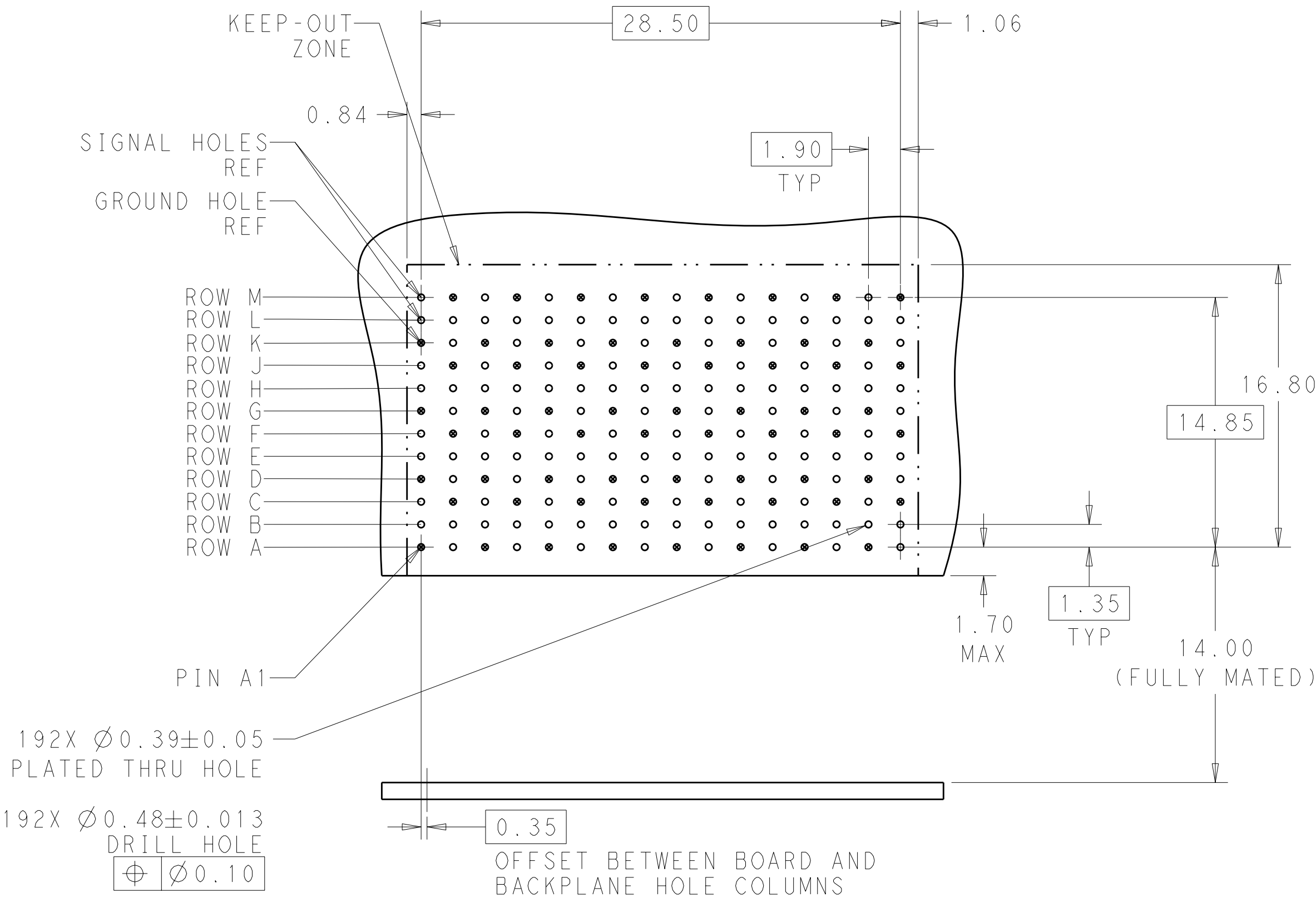


- 1 MATERIAL:
HOUSING: LCP, GLASS FILLED, UL94V-0.
TERMINALS: HIGH PERFORMANCE COPPER ALLOY.
- 2 FINISH:
30μ" SELECTIVE GOLD IN CONTACT AREA. SELECTIVE TIN ON PCB TAILS, NICKEL OVERALL.
- 3 FINISH:
30μ" SELECTIVE GOLD IN CONTACT AREA. SELECTIVE TIN-LEAD ON PCB TAILS, NICKEL OVERALL.



SCALE 4:1

REFER TO WWW.TE.COM
FOR PRODUCT AVAILABILITY



RECOMMENDED PCB LAYOUT
MIN BOARD THICKNESS 1.0

NONE	3	2007723-5
NONE	2	2007723-1
KEY POSITION	FINISH	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	18MAY2011	TE Connectivity	
		CHK	18MAY2011		
		APVD	18MAY2011		
		PRODUCT SPEC			
		APPLICATION SPEC			
		WEIGHT			
		CUSTOMER DRAWING			
		SCALE	6:1		
		SHEET	1		
		OF	1		
		REV	B		

D

C

B

A